AI-Powered PCB Engineering Forum

Xpedition Standard 2604 Update & Demo

이디앤씨 / 허소은 대리

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Agenda

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- Xpedition Standard
- Xpedition Standard – 5가지 주요 기술 요소
- Xpedition Standard 2604 Update & Demo
- Summary

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Xpedition Standard

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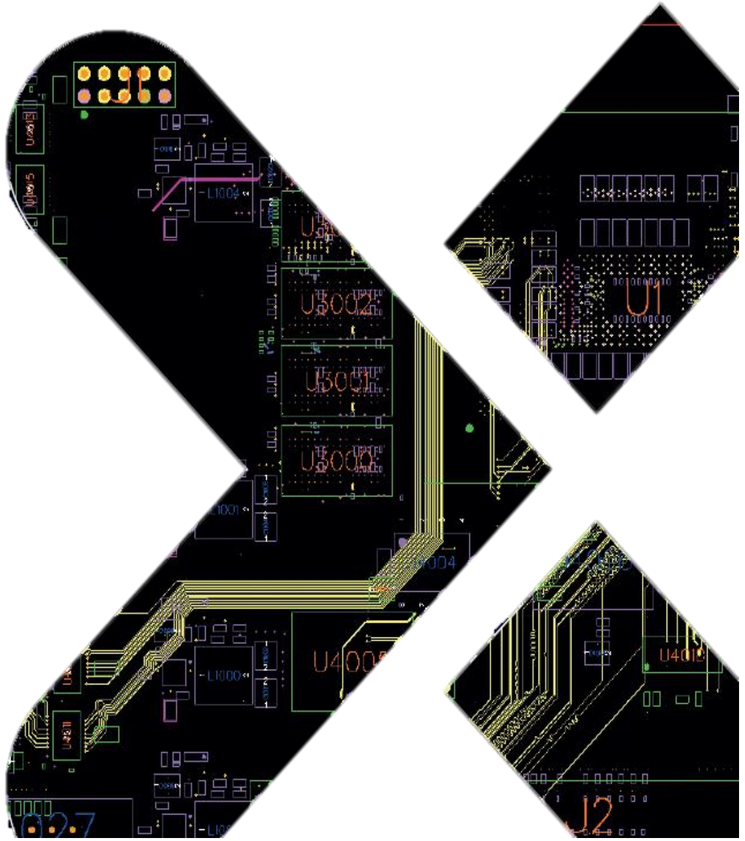

- Xpedition 기술 기반
- 합리적 비용
- 효율적인 협업 환경
- AI 기반 효율성

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Xpedition Standard – 5가지 주요 기술 요소

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Electronic Design & Communication

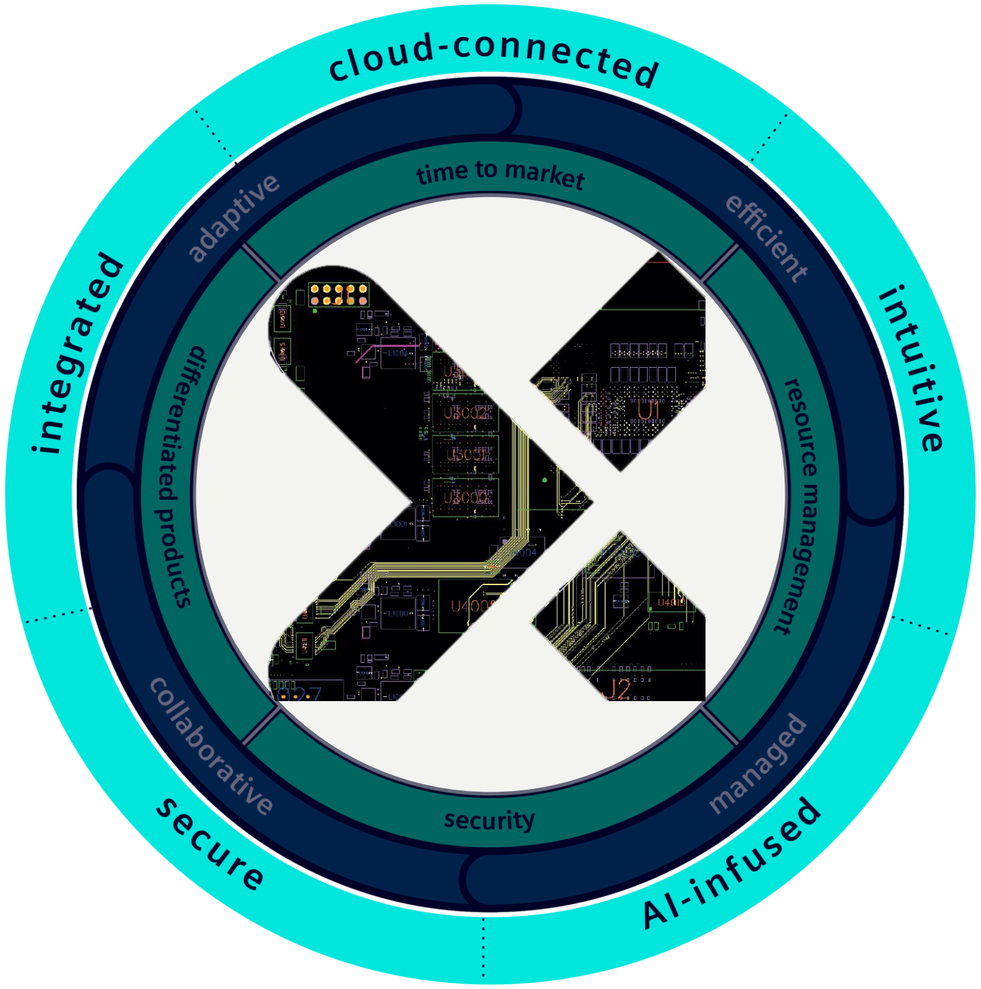
Intuitive
Modern UX를 활용한 생산성 향상

AI-infused
설계 최적화 및 자동화

Cloud-connected
데스크톱 툴과 클라우드 연결

Integrated
PCB 설계 프로세스 통합

Secure
중요한 설계 IP 보호



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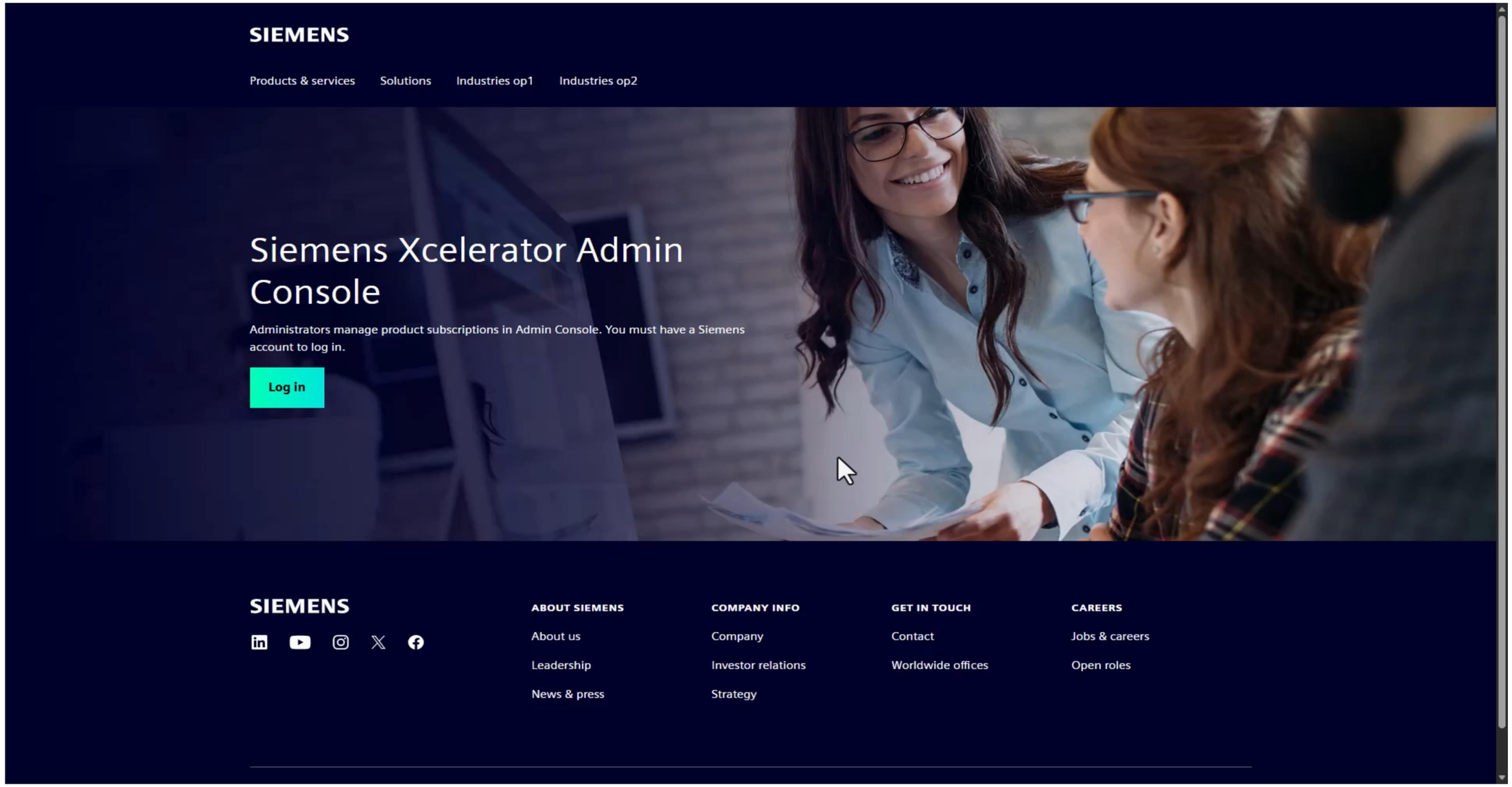
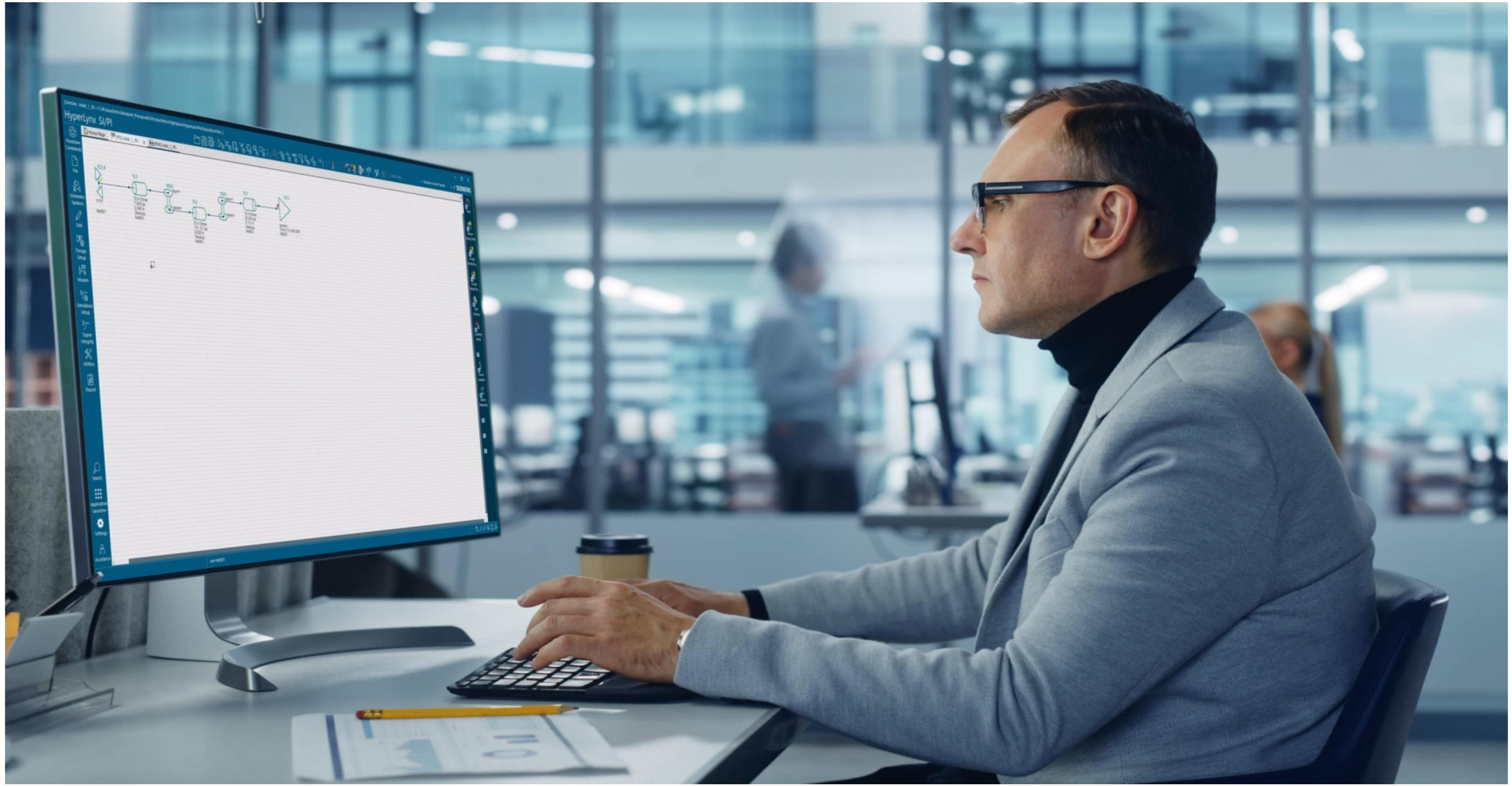
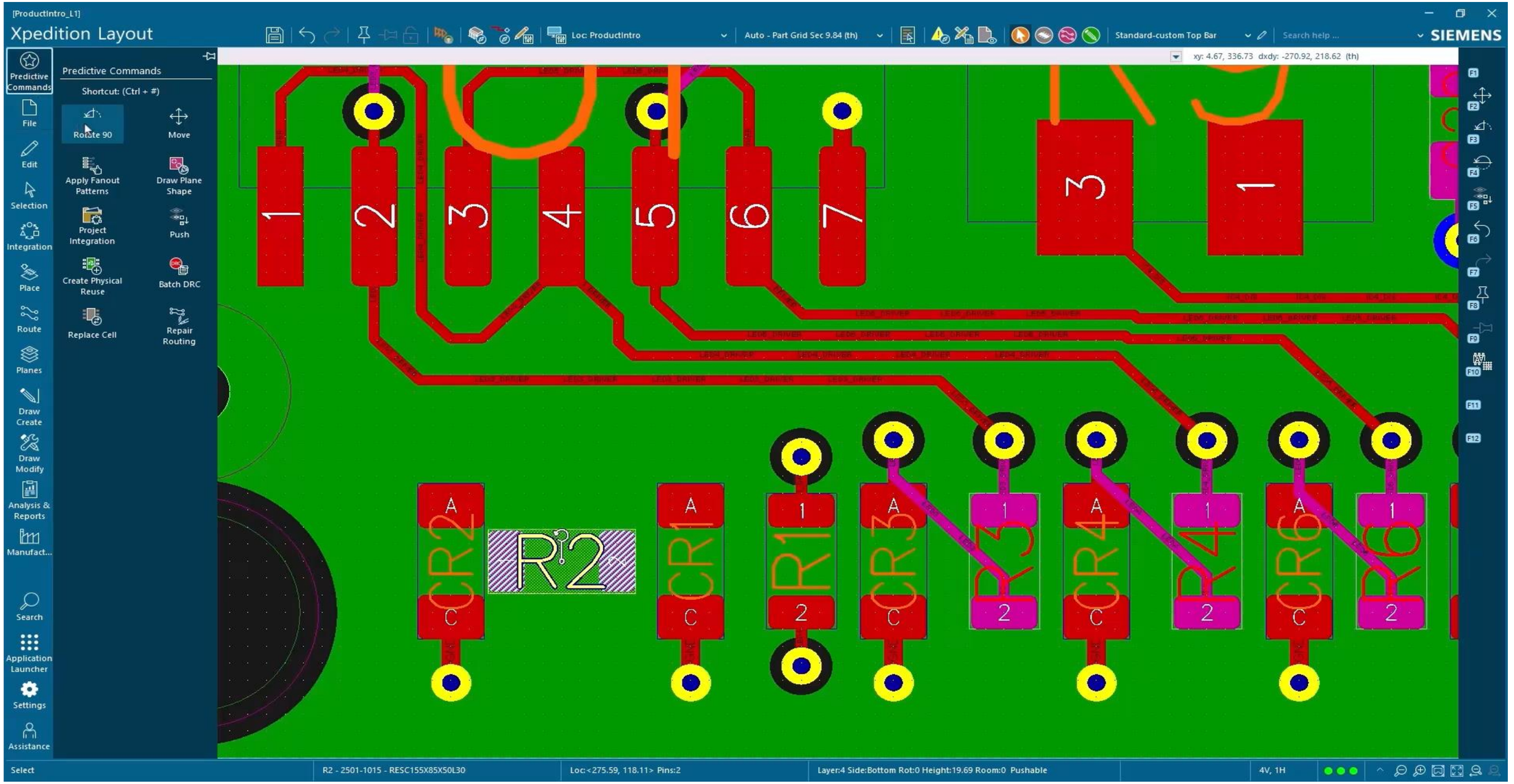
Named user licensing



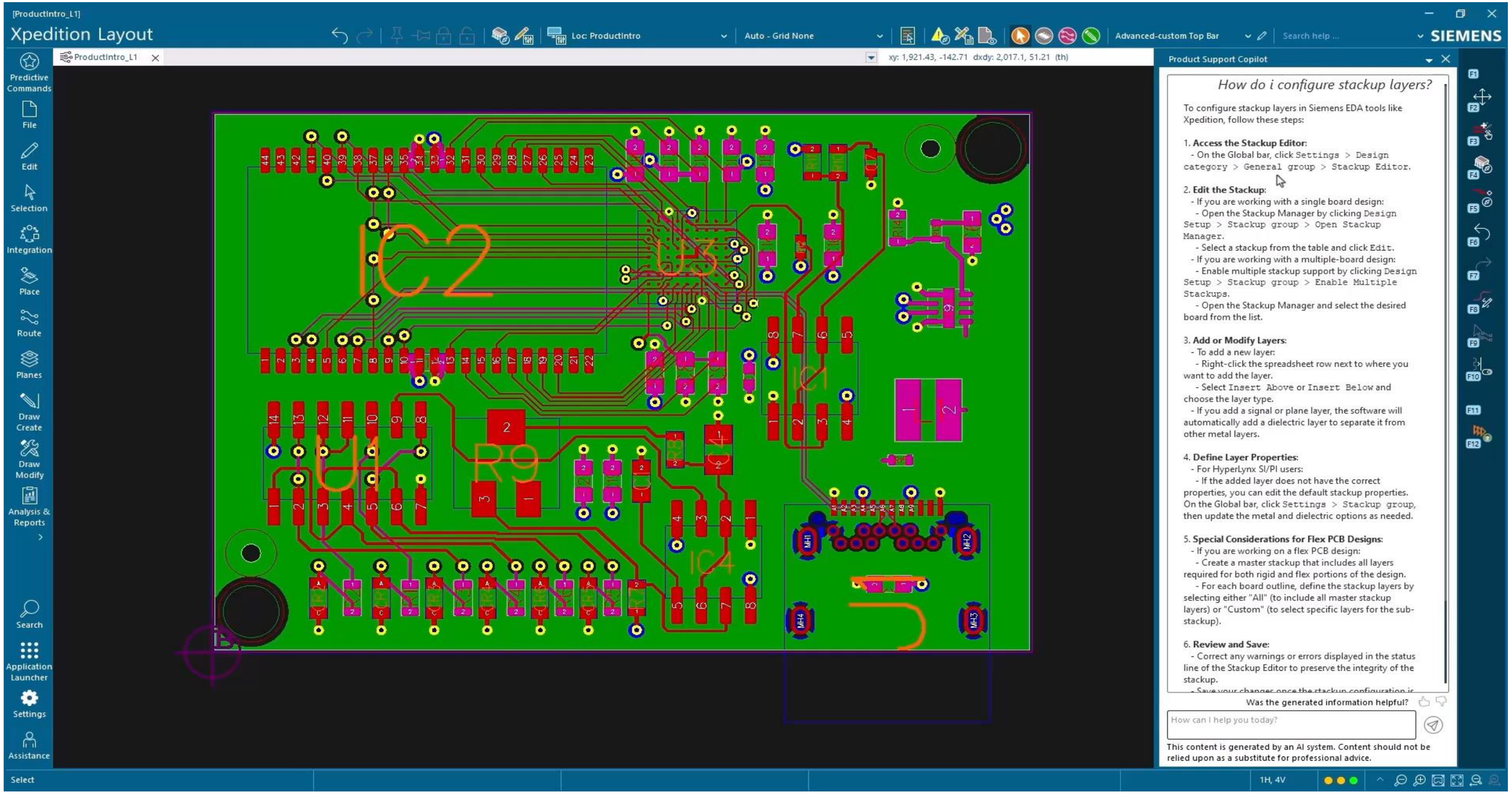
Token-based add-ons



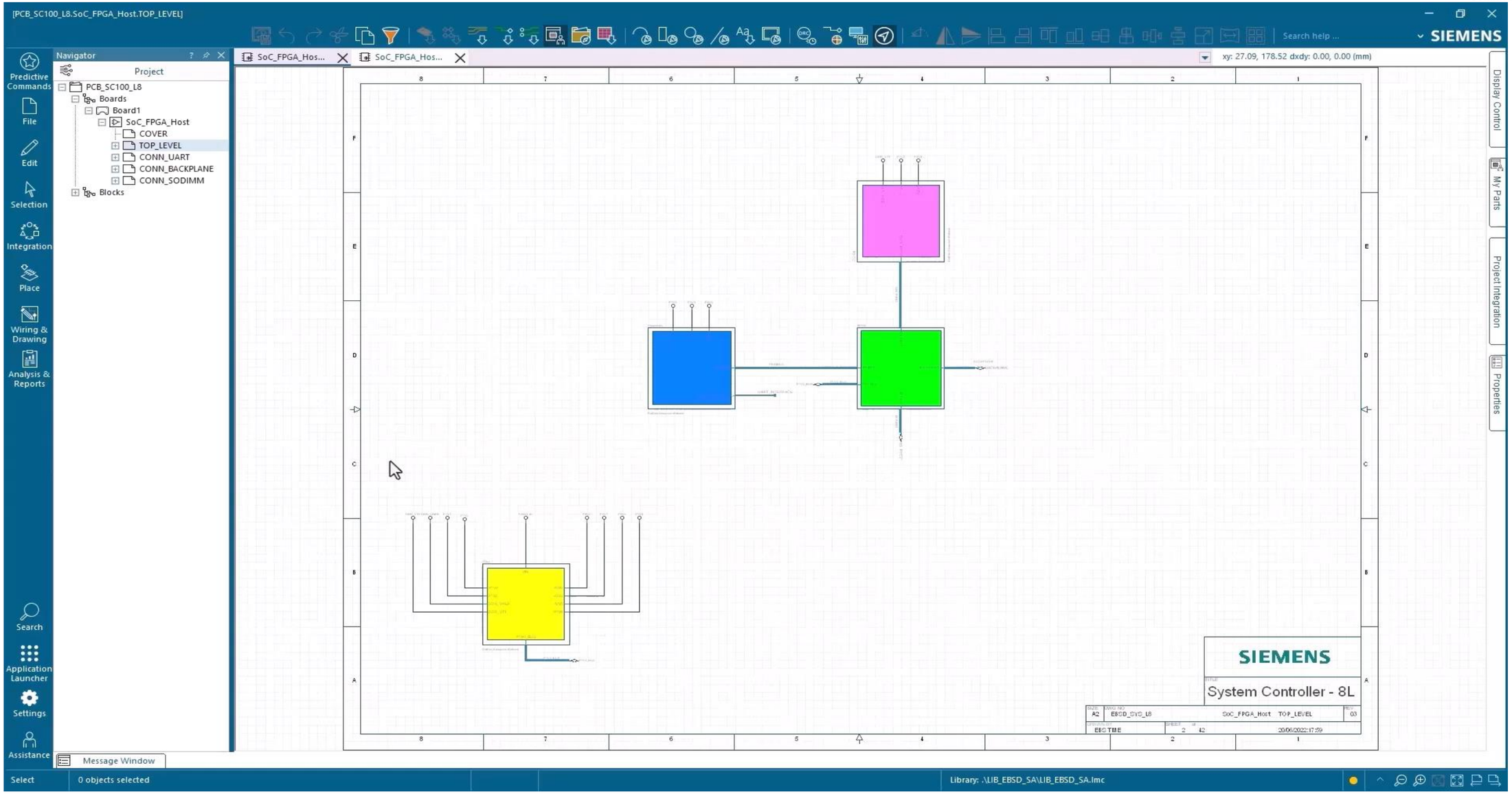
Global search and AI command prediction



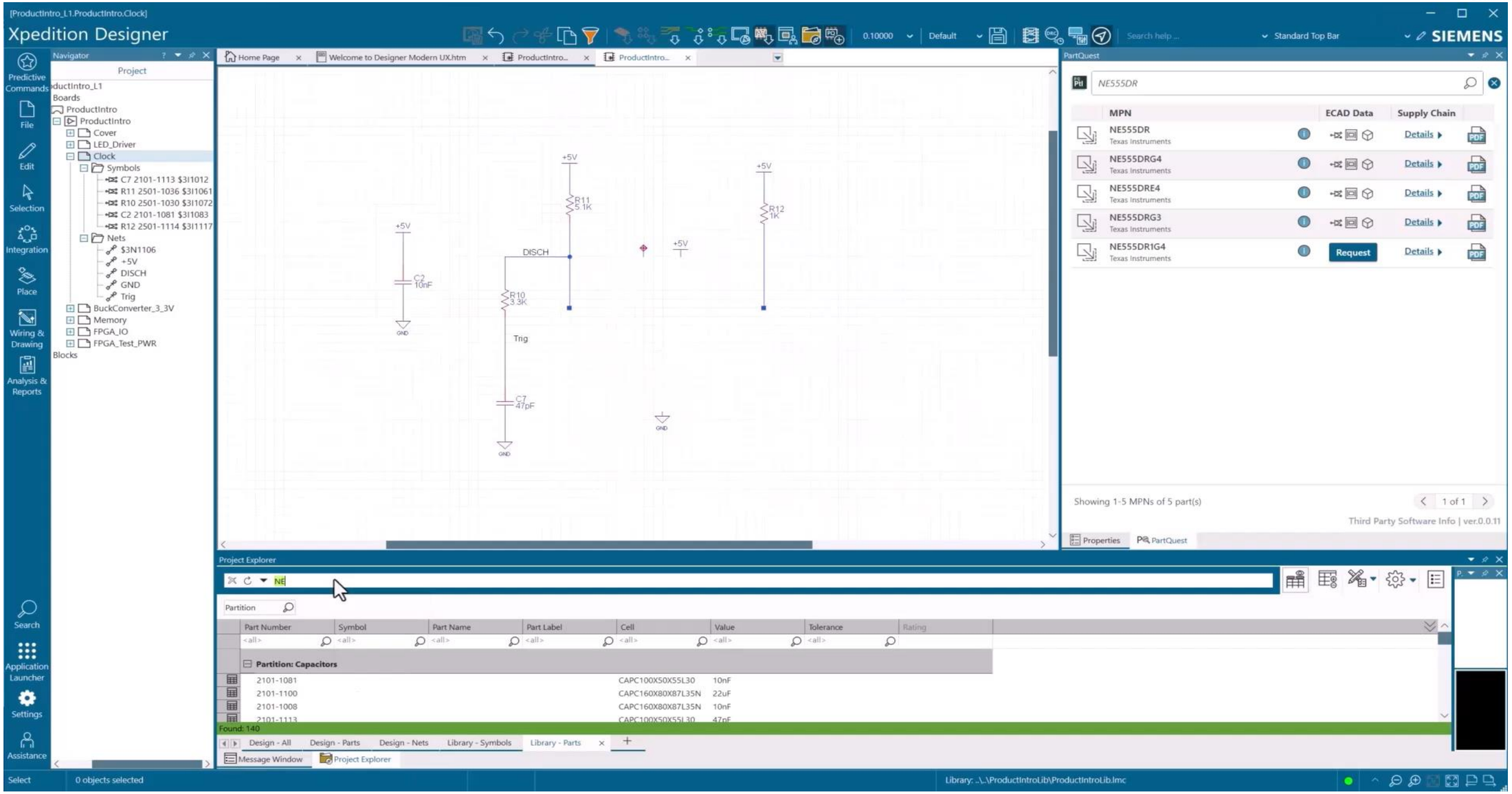
Product support copilot



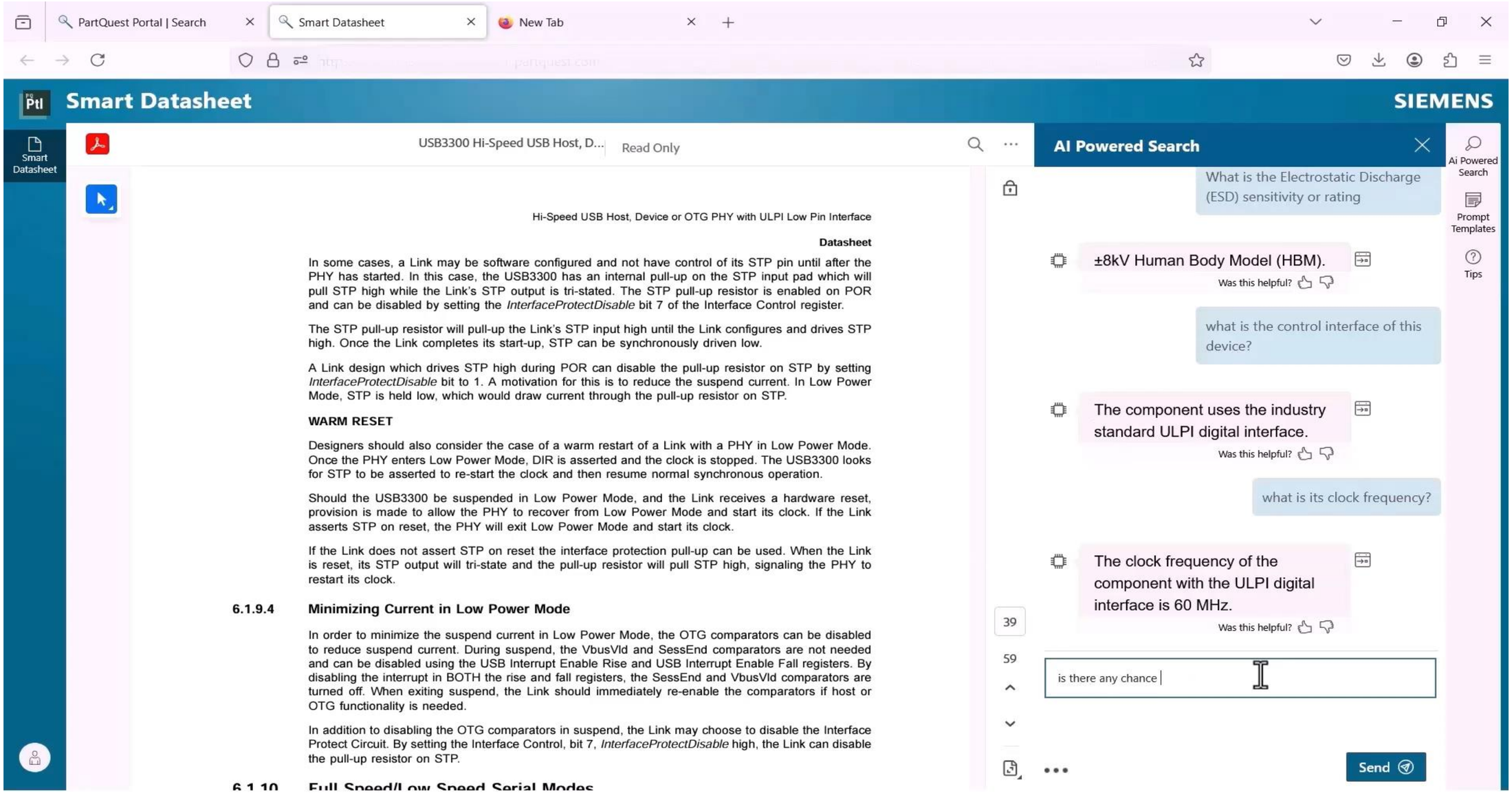
Schematic capture



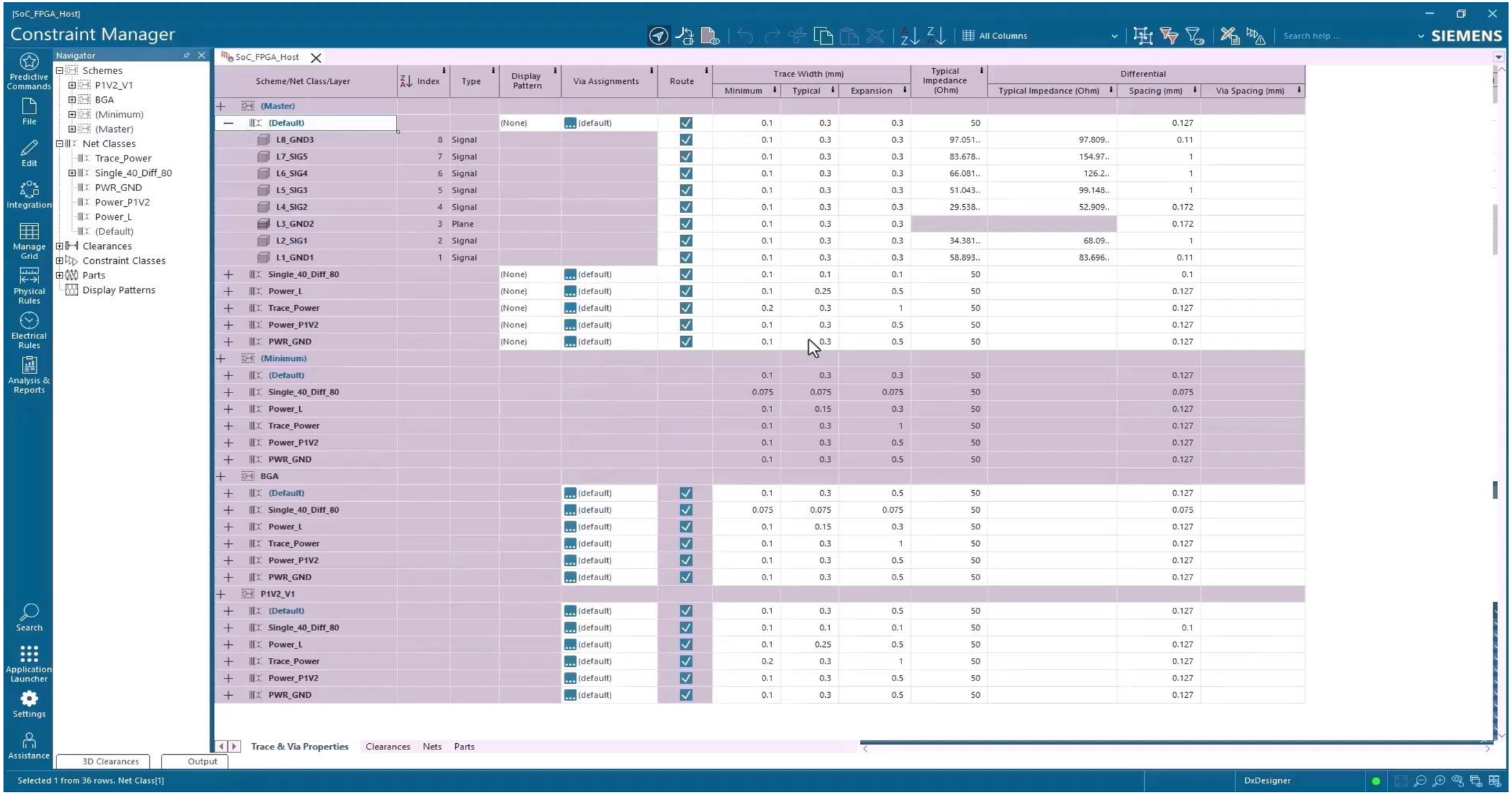
Component sourcing and research



AI-assisted smart datasheet research

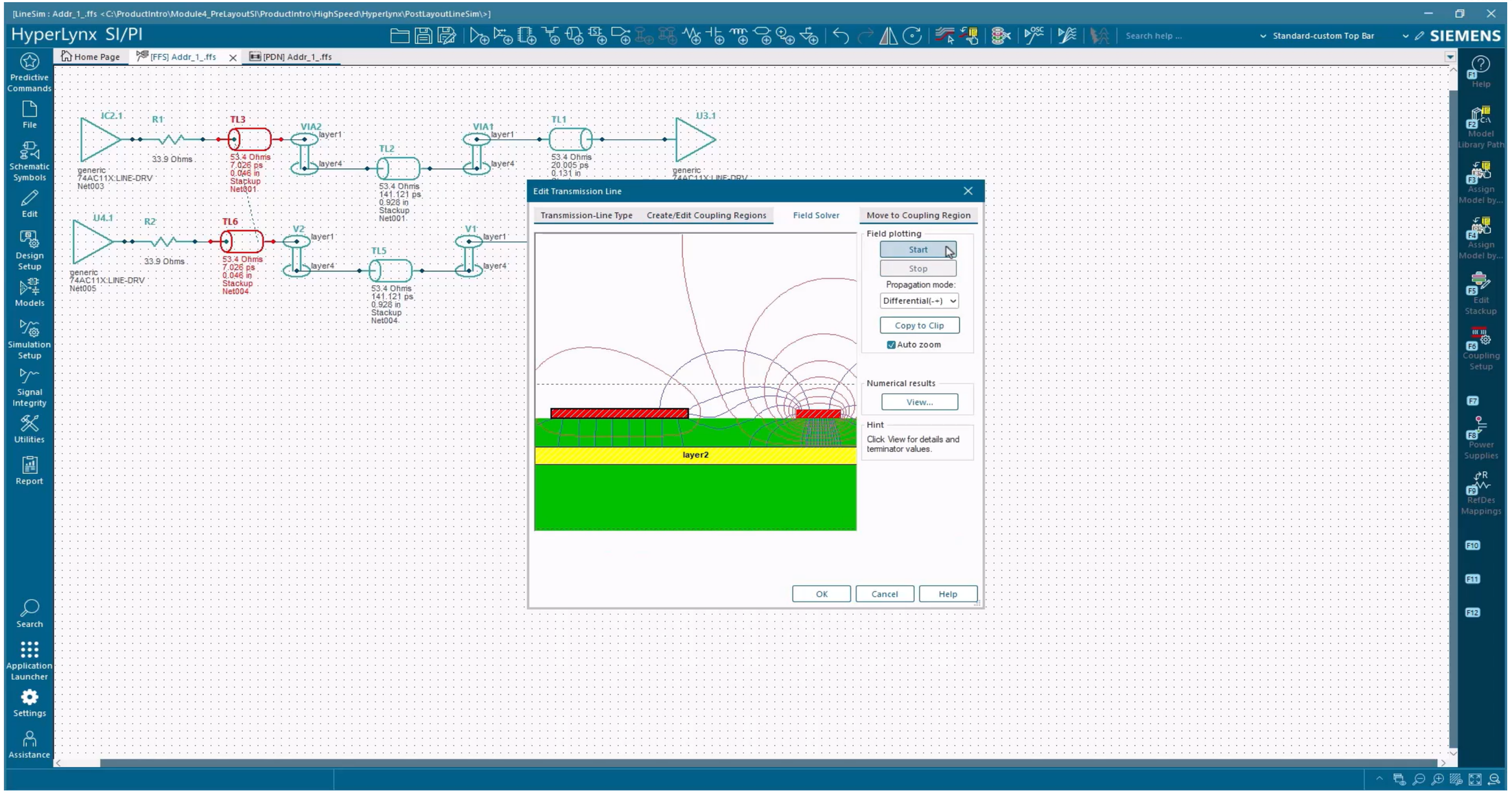


Integrated constraint management

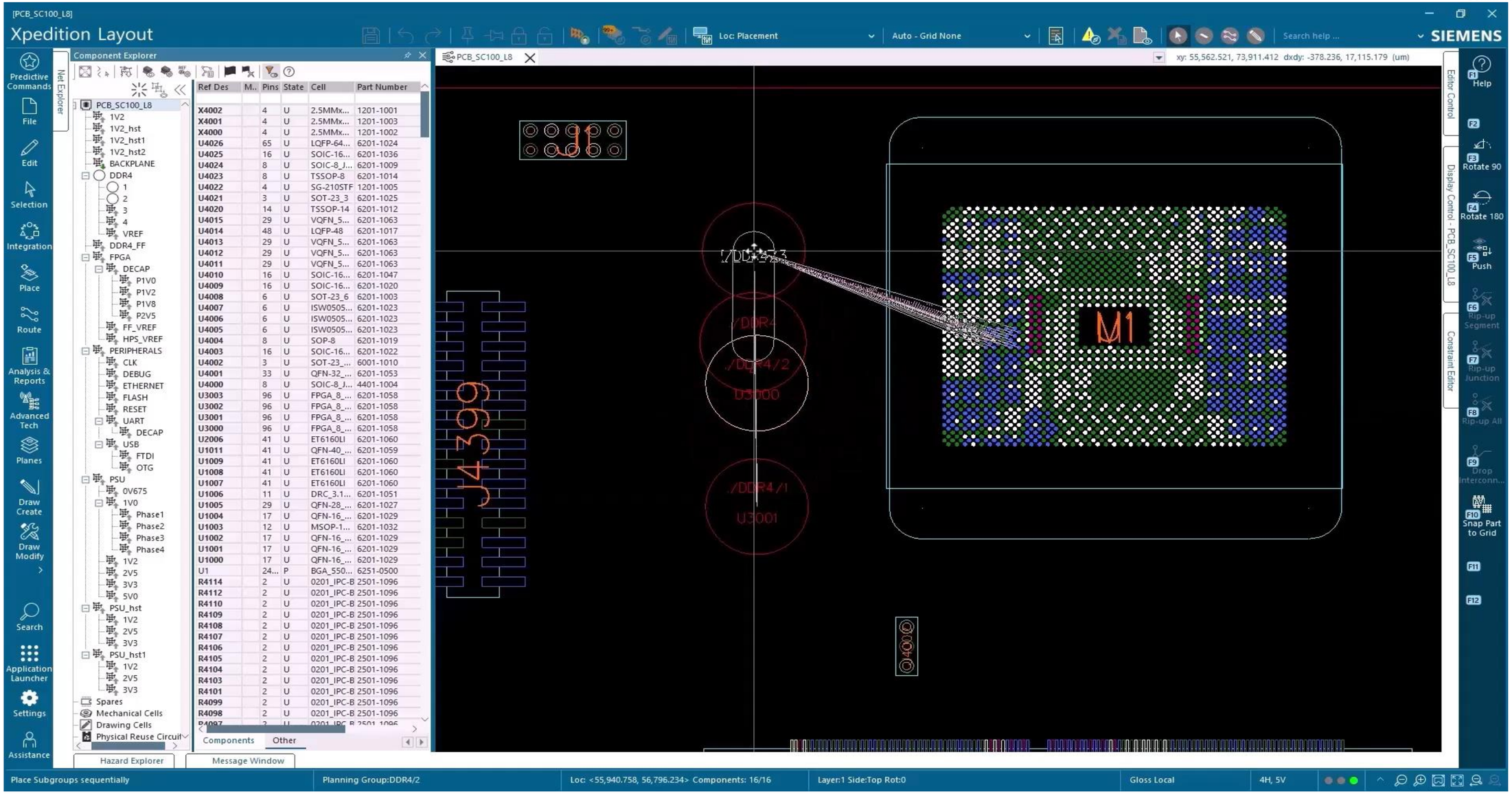


Scheme/Net Class/Layer	Index	Type	Display Pattern	Via Assignments	Route	Trace Width (mm) Minimum	Trace Width (mm) Typical	Trace Width (mm) Expansion	Typical Impedance (Ohm)	Differential Typical Impedance (Ohm)	Differential Spacing (mm)	Differential Via Spacing (mm)
(Master)												
(Default)			(None)	(default)	☑	0.1	0.3	0.3	50		0.127	
L8_GND3	8	Signal			☑	0.1	0.3	0.3	97.051..	97.809..	0.11	
L7_SIG5	7	Signal			☑	0.1	0.3	0.3	83.678..	154.97..	1	
L6_SIG4	6	Signal			☑	0.1	0.3	0.3	66.081..	126.2..	1	
L5_SIG3	5	Signal			☑	0.1	0.3	0.3	51.043..	99.148..	1	
L4_SIG2	4	Signal			☑	0.1	0.3	0.3	29.538..	52.909..	0.172	
L3_GND2	3	Plane			☑	0.1	0.3	0.3			0.172	
L2_SIG1	2	Signal			☑	0.1	0.3	0.3	34.381..	68.09..	1	
L1_GND1	1	Signal			☑	0.1	0.3	0.3	58.893..	83.696..	0.11	
Single_40_Diff_80			(None)	(default)	☑	0.1	0.1	0.1	50		0.1	
Power_L			(None)	(default)	☑	0.1	0.25	0.5	50		0.127	
Trace_Power			(None)	(default)	☑	0.2	0.3	1	50		0.127	
Power_P1V2			(None)	(default)	☑	0.1	0.3	0.5	50		0.127	
PWR_GND			(None)	(default)	☑	0.1	0.3	0.5	50		0.127	
(Minimum)												
(Default)						0.1	0.3	0.3	50		0.127	
Single_40_Diff_80						0.075	0.075	0.075	50		0.075	
Power_L						0.1	0.15	0.3	50		0.127	
Trace_Power						0.1	0.3	1	50		0.127	
Power_P1V2						0.1	0.3	0.5	50		0.127	
PWR_GND						0.1	0.3	0.5	50		0.127	
BGA												
(Default)				(default)	☑	0.1	0.3	0.5	50		0.127	
Single_40_Diff_80				(default)	☑	0.075	0.075	0.075	50		0.075	
Power_L				(default)	☑	0.1	0.15	0.3	50		0.127	
Trace_Power				(default)	☑	0.1	0.3	1	50		0.127	
Power_P1V2				(default)	☑	0.1	0.3	0.5	50		0.127	
PWR_GND				(default)	☑	0.1	0.3	0.5	50		0.127	
P1V2_V1												
(Default)				(default)	☑	0.1	0.3	0.5	50		0.127	
Single_40_Diff_80				(default)	☑	0.1	0.1	0.1	50		0.1	
Power_L				(default)	☑	0.1	0.25	0.5	50		0.127	
Trace_Power				(default)	☑	0.2	0.3	1	50		0.127	
Power_P1V2				(default)	☑	0.1	0.3	0.5	50		0.127	
PWR_GND				(default)	☑	0.1	0.3	0.5	50		0.127	

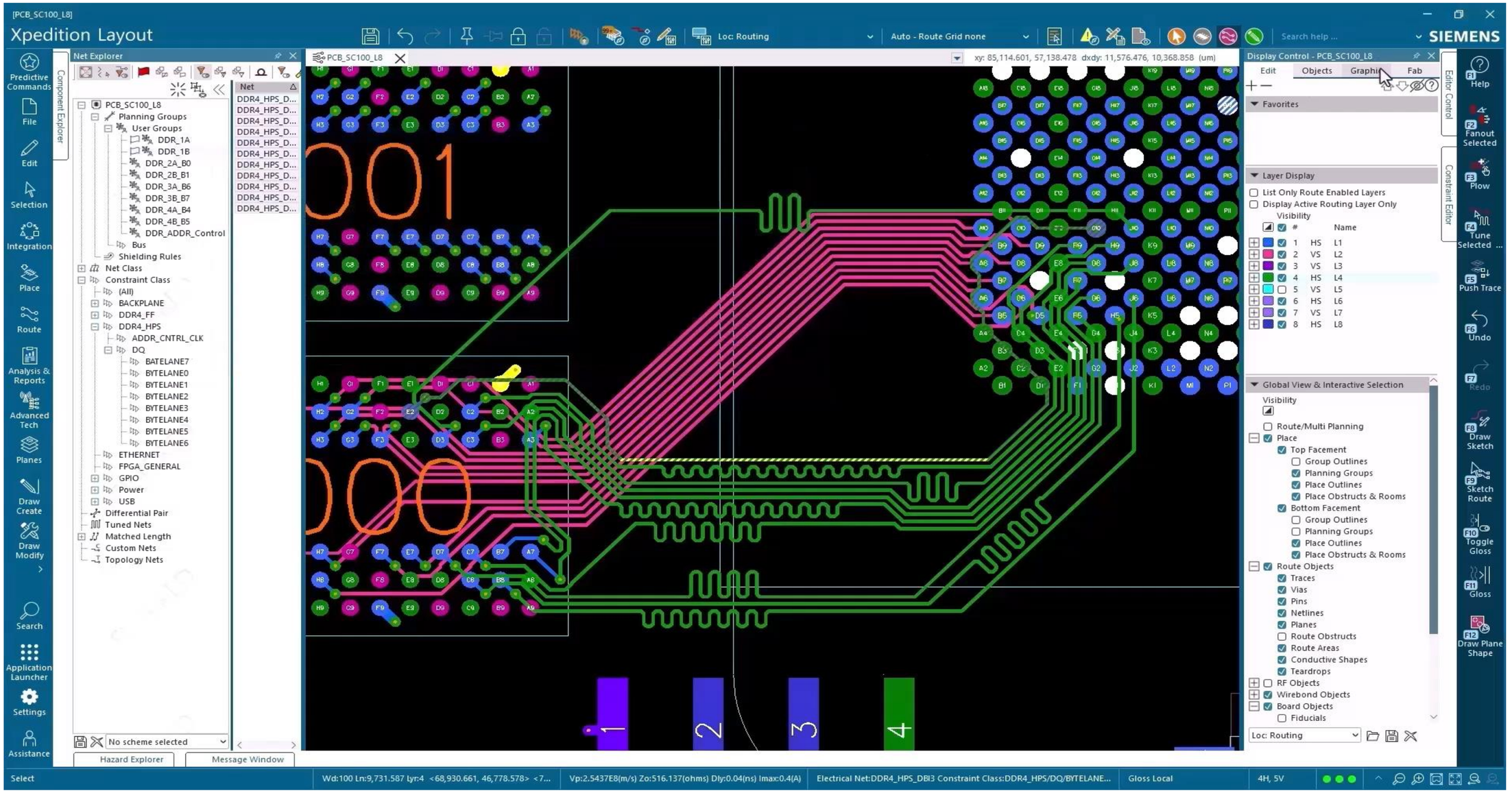
Pre-layout signal integrity



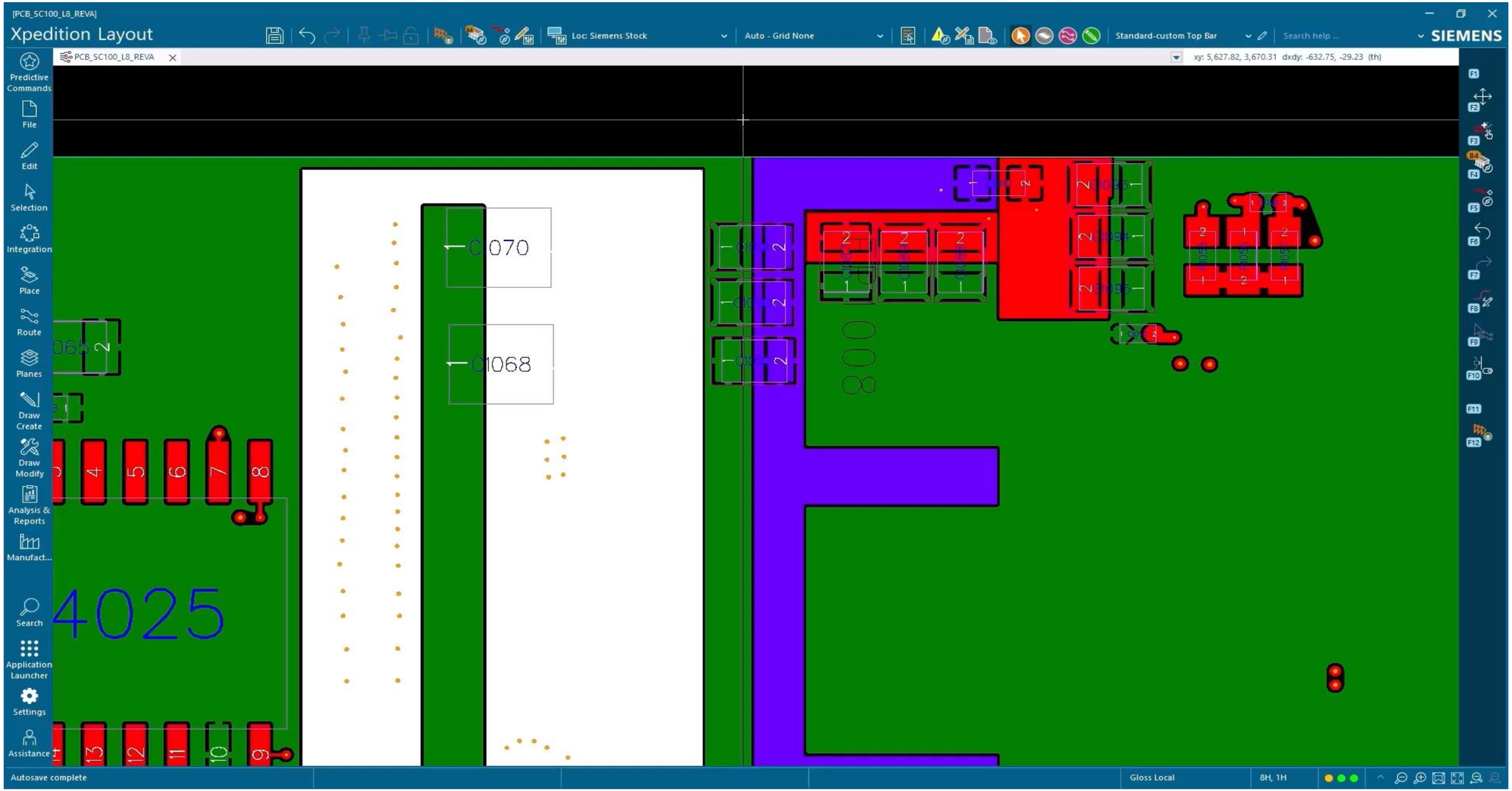
Component planning & placement



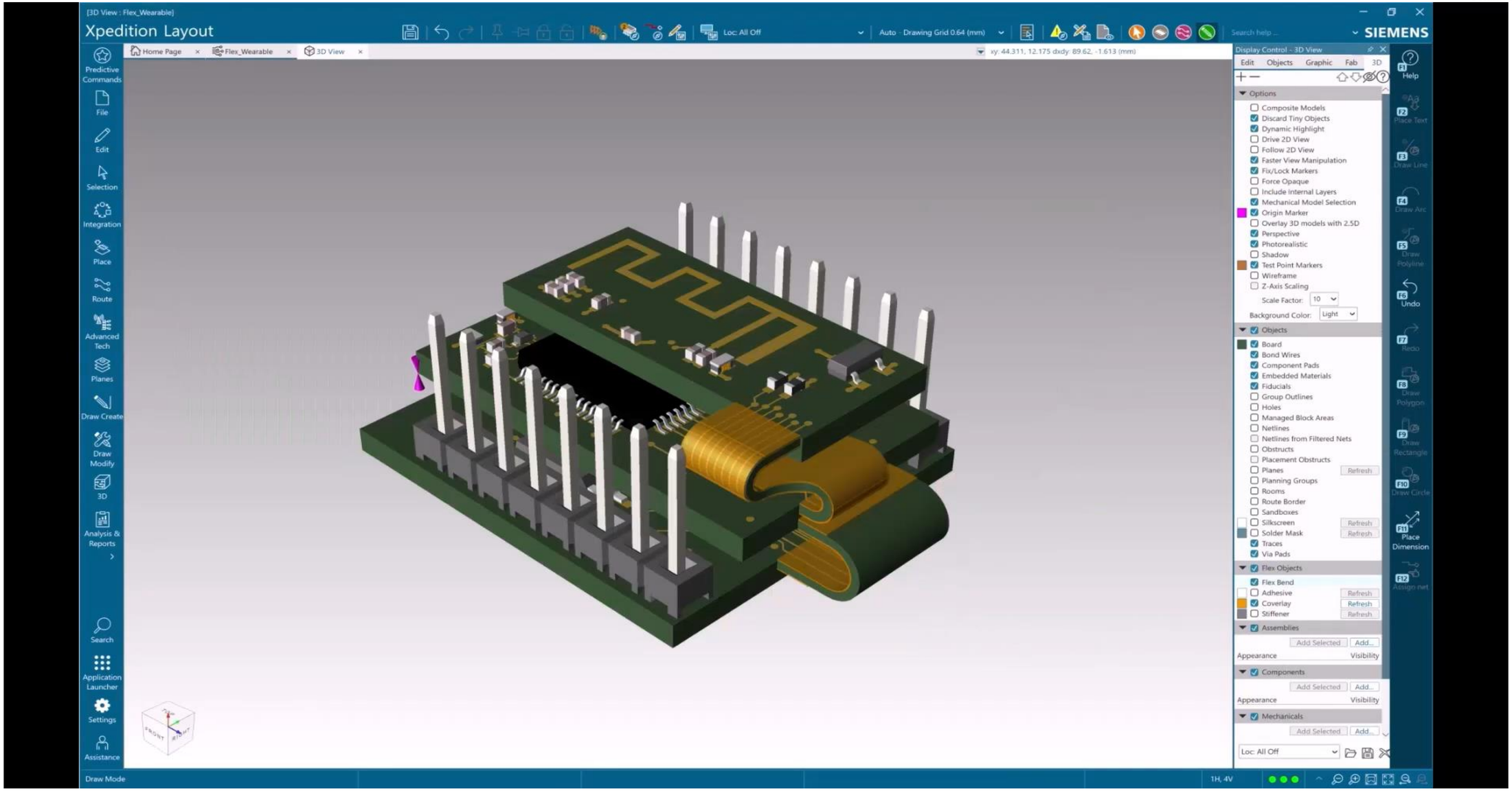
Connectivity routing



Physical reuse



Rigid-flex


[3D View : Flex_Wearable]
Xpedition Layout
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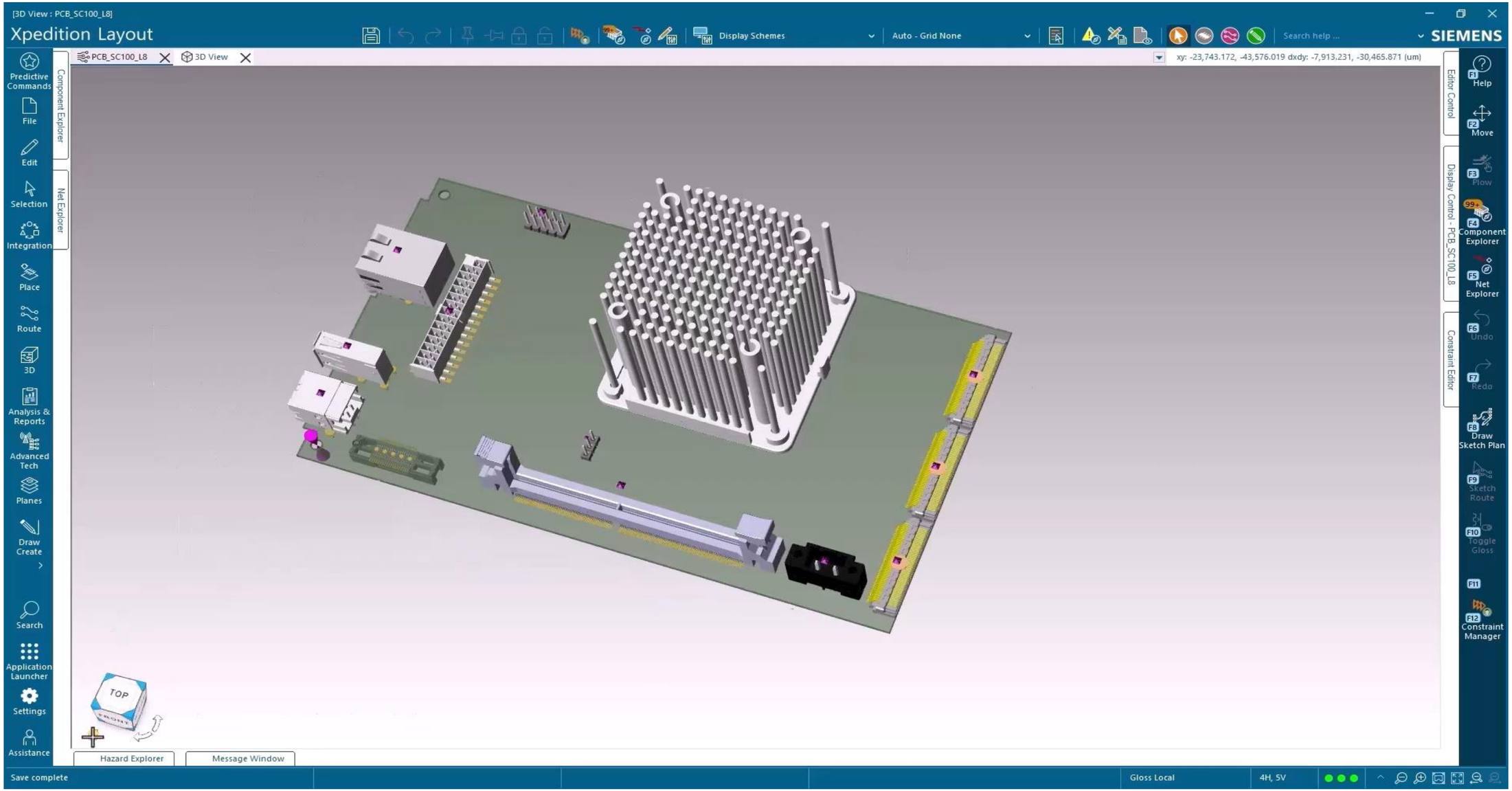
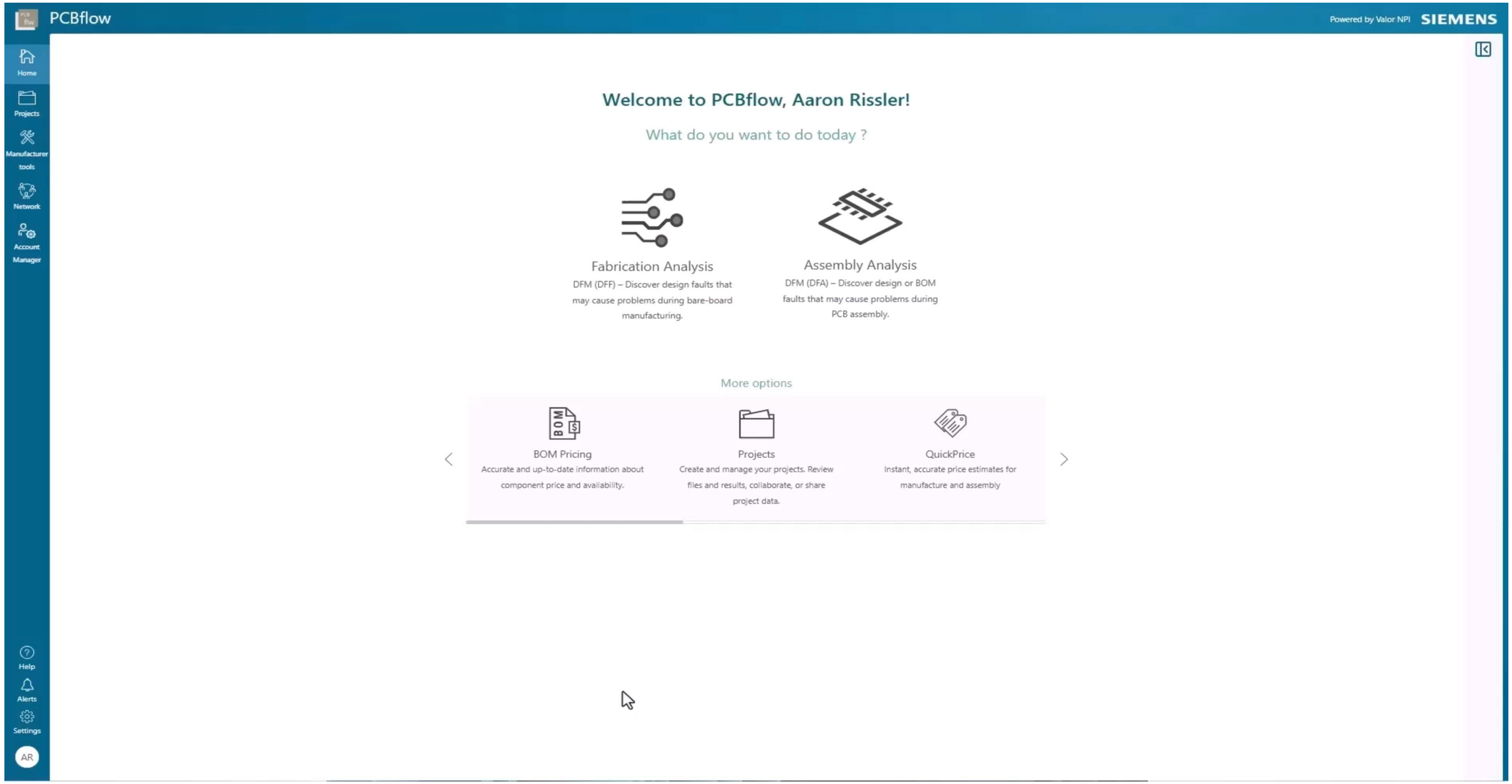
Home Page
Flex_Wearable
3D View
Predictive Commands
File
Edit
Selection
Integration
Place
Route
Advanced Tech
Planes
Draw Create
Draw Modify
3D
Analysis & Reports
Search
Application Launcher
Settings
Assistance
Display Control - 3D View
Edit
Objects
Graphic
Fab
3D
Options
Composite Models
Discard Tiny Objects
Dynamic Highlight
Drive 2D View
Follow 2D View
Faster View Manipulation
Fix/Lock Markers
Force Opaque
Include Internal Layers
Mechanical Model Selection
Origin Marker
Overlay 3D models with 2.5D
Perspective
Photorealistic
Shadow
Test Point Markers
Wireframe
Z-Axis Scaling
Scale Factor:
Background Color:
Light
Objects
Board
Bond Wires
Component Pads
Embedded Materials
Fiducials
Group Outlines
Holes
Managed Block Areas
Netlines
Netlines from Filtered Nets
Obstructs
Placement Obstructs
Planes
Planning Groups
Rooms
Route Border
Sandboxes
Silkscreen
Solder Mask
Traces
Via Pads
Flex Objects
Flex Bend
Adhesive
Coverlay
Stiffener
Assemblies
Components
Mechanicals
Appearance
Visibility
Add Selected
Add...
Refresh
Loc: All Off
Help
Place Text
Draw Line
Draw Arc
Draw Polyline
Undo
Redo
Draw Polygon
Draw Rectangle
Draw Circle
Place Dimension
Assign net
Draw Mode
1H, 4V

ECAD/MCAD co-design



Actionable DFM analysis



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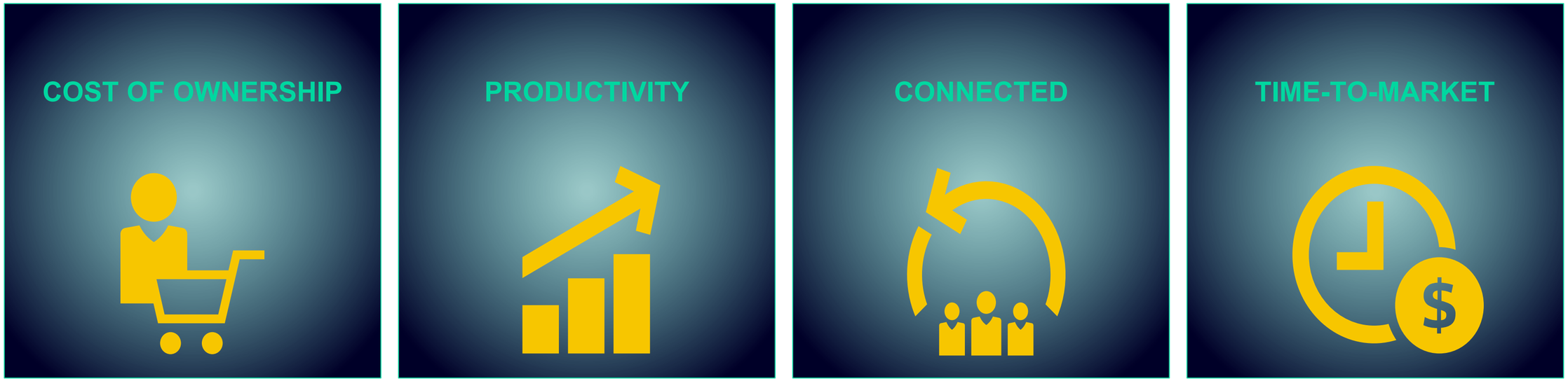

Ease-of-Use	**A next-gen UX that simplifies and integrates the entire end-2-end flow**
Accelerated Design	**Automation and embedded AI automates tasks, optimizes design to accelerate TTM**
Connected Ecosystem	**Real-time teamwork enabled across tools, teams, and supply chain**
Scalable	**Xpedition technology continuum that scales with needs and budget**

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